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东莞市合康电子有限公司
Dongguan Hekang Electronic co., LTD

Chip Antenna

承 认 书

客户接受

This Specifications is received

签 章 SIGN:

接受日 DATE:

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2.4GHz 2012 Chip Antenna: ANT2012R24005KL0

Applications:

WLAN, 802.11b/g, Bluetooth, etc...

Features

SMD, high reliability, ultra compact, Omni-directional...



Part number

ANT 2012 R 2400 5K L0
(1) (2) (3) (4) (5)

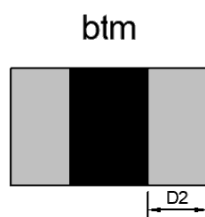
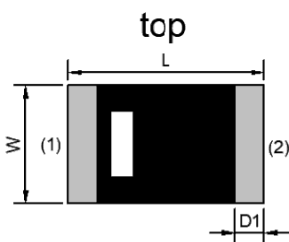
(1) Size Code	2.0x1.2mm
(2) Packing	Tape and reel
(3) Frequency	2.4GHz
(4) Packing Number	5K
(5) Code	L0

Electrical Specification

Working Frequency Range	2400 ~2484 MHz
Peak Gain	1.01 dBi (Typ.)
Impedance	50 Ohm
VSWR	2.5 (Max)
Polarization	Linear
Azimuth Beamwidth	Omni-directional
Operation Temperature(°C)	-40~85(°C)

The specification is defined on EVB.

Dimension and Terminal Configuration

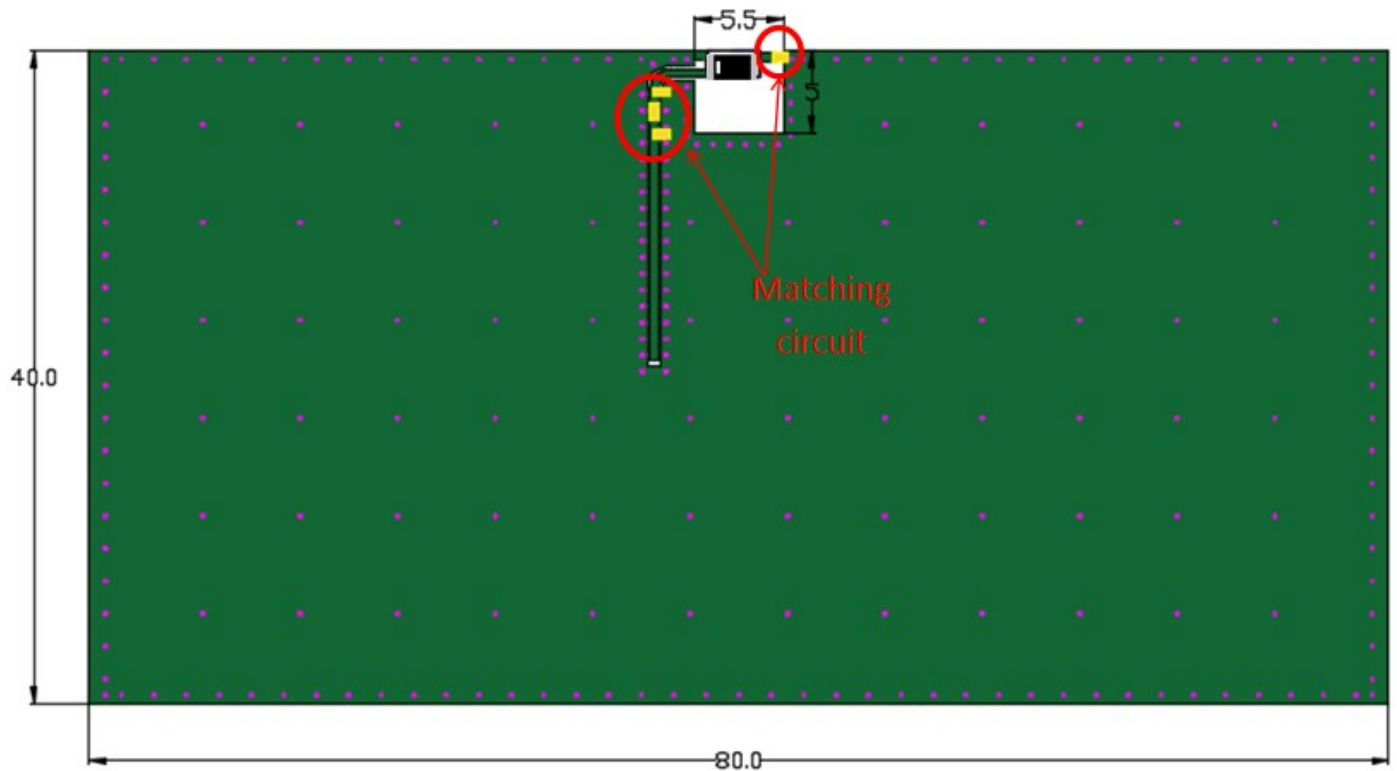


Dimension (mm)	
L	2.00±0.15
W	1.20±0.15
T	0.50±0.10
D1	0.30±0.15
D2	0.60±0.15

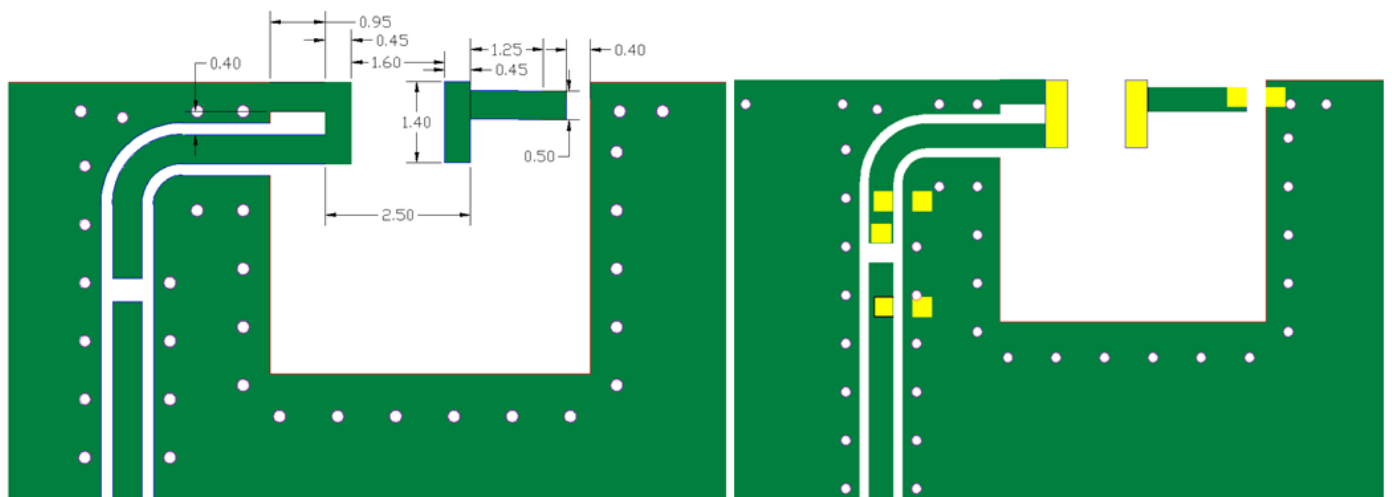
No.	Terminal Name
1	Feeding
2	GND

Evaluation Board Reference

PCB Dimension



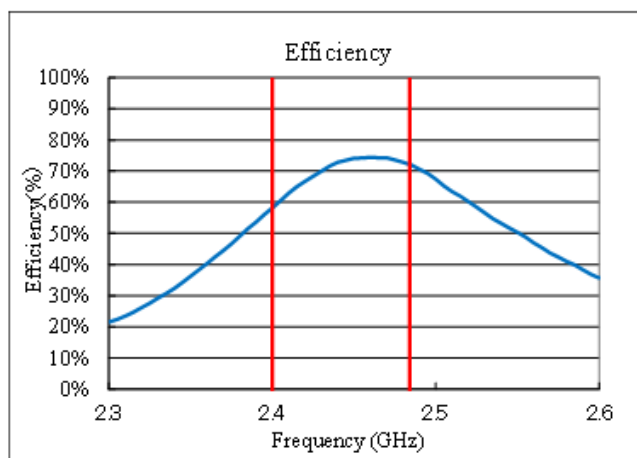
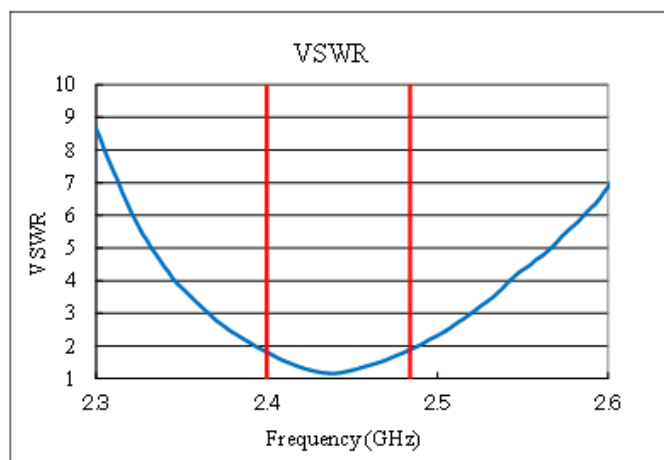
Antenna Layout Reference



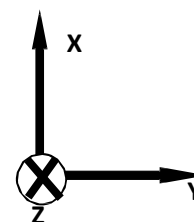
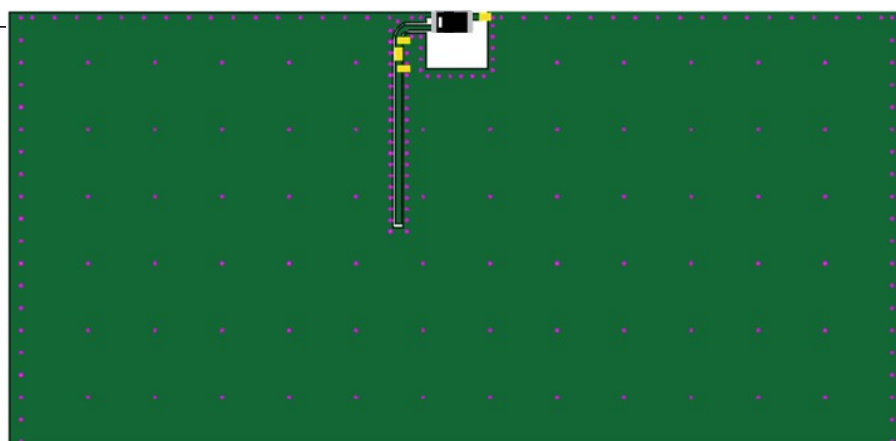
Unit : mm

Electrical Characteristics

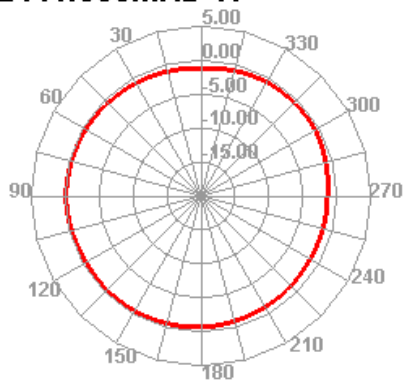
VSWR&Efficiency



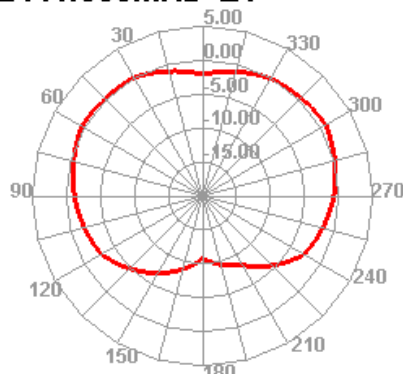
Radiation Pattern



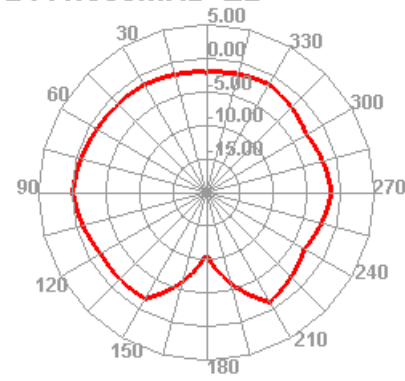
2441.000MHz H



2441.000MHz E1



2441.000MHz E2

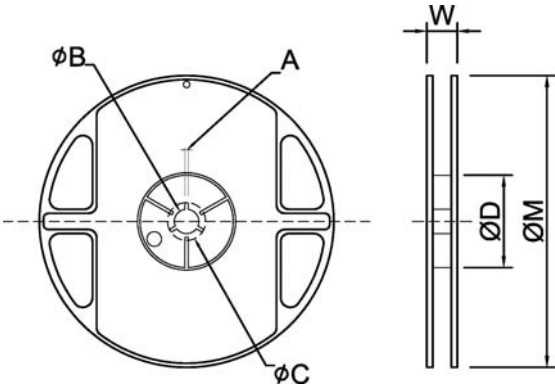


Frequency (MHz)	2400	2450	2480
Peck Gain (dBi)	0.85	1.01	0.82
Efficiency (%)	62.06	72.02	75.01

Taping Specifications

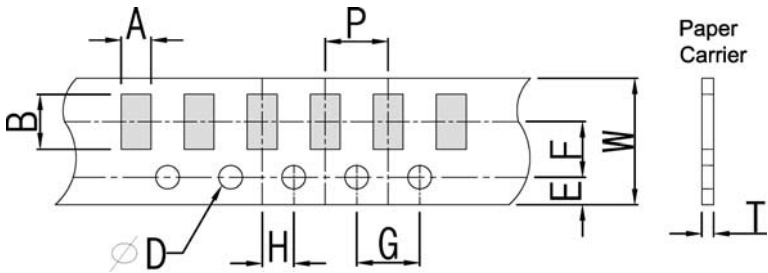
Reel and Taping Specification

Reel Specification



TYPE	SIZE		A	ψB	ψC	ψD	W	ψM
2012	7"	5K/Reel	2.0±0.5	13.5±1.0	21±1.0	60±1.0	11.5±2.0	178±2.0

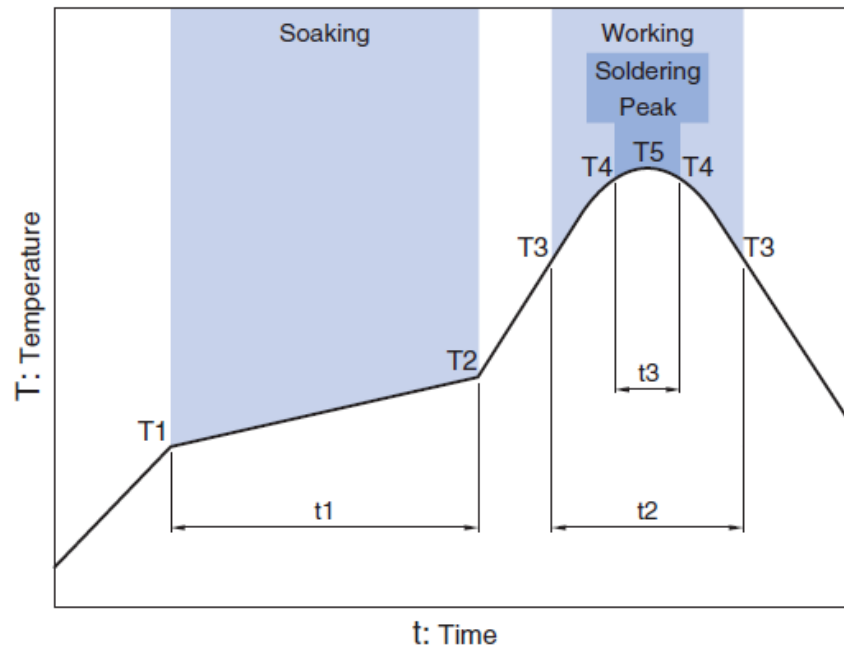
Tapping Specification



Packaging	Type	A	B	W	E	F	G	H	T	ψD	P
Paper Type	2012	1.50±0.20	2.20±0.20	8.0±0.20	1.75±0.10	3.5±0.05	4.0±0.10	2.0±0.05	0.80±0.10	1.50 ^{+0.10} ₋₀	4.0±0.1

2.4GHz 2012 Chip Antenna: ANT2012R24005KL0**Recommended Reflow Profile**

Pb free solder



Soaking			Working		Soldering		Peak
Temp.		Time	Temp.	Time	Temp.	Time	Temp.
T1	T2	t1	T3	t2	T4	t3	T5
150°C	180°C	60 to 120sec	230°C	more than 30sec	247 to 253°C	within 10sec	260°C Max.

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